

FEATURES

12-Bit Resolution

Low Gain TC: 2 ppm/°C typ

Fast TTL Compatible Data Latches

Single +5 V to +15 V Supply

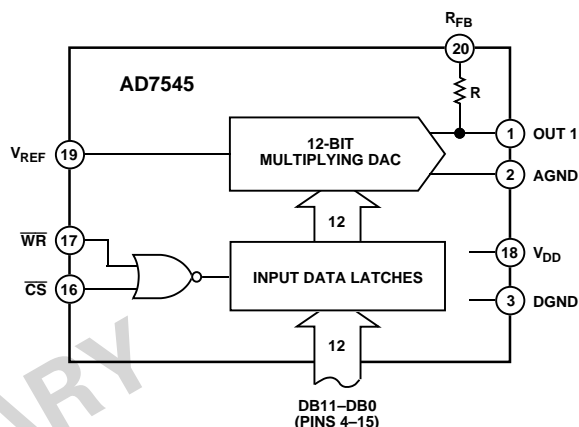
Small 20-Lead 0.3" DIP and 20-Terminal Surface Mount Packages

Latch Free (Schottky Protection Diode Not Required)

Low Cost

Ideal for Battery Operated Equipment

FUNCTIONAL BLOCK DIAGRAM



GENERAL DESCRIPTION

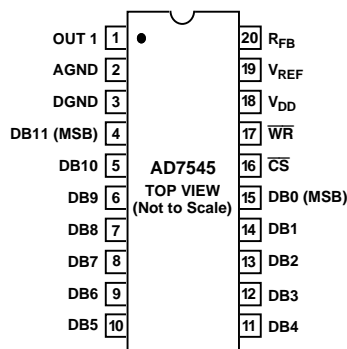
The AD7545 is a monolithic 12-bit CMOS multiplying DAC with onboard data latches. It is loaded by a single 12-bit wide word and directly interfaces to most 12- and 16-bit bus systems. Data is loaded into the input latches under the control of the \overline{CS} and \overline{WR} inputs; tying these control inputs low makes the input latches transparent, allowing direct unbuffered operation of the DAC.

The AD7545 is particularly suitable for single supply operation and applications with wide temperature variations.

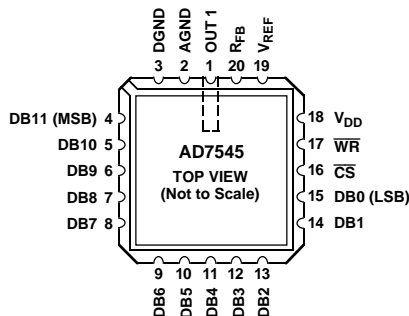
The AD7545 can be used with any supply voltage from +5 V to +15 V. With CMOS logic levels at the inputs the device dissipates less than 0.5 mW for $V_{DD} = +5$ V.

PIN CONFIGURATIONS

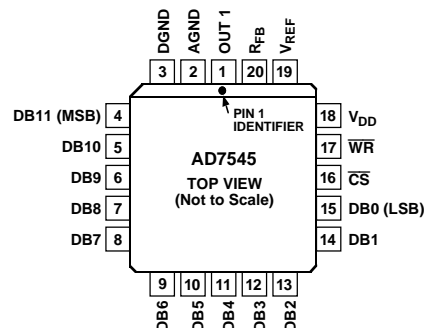
DIP



LCCC



PLCC



REV. A

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AD7545—SPECIFICATIONS (V_{REF} = +10 V, V_{OUT1} = 0 V, AGND = DGND unless otherwise noted)

		V _{DD} = +5 V Limits		V _{DD} = +15 V Limits				
Parameter	Version	T _A = +25°C	T _{MIN} , T _{MAX} ¹	T _A = +25°C	T _{MIN} , T _{MAX} ¹	Units	Test Conditions/Comments	
STATIC PERFORMANCE								
Resolution	All	12	12	12	12	Bits	10-Bit Monotonic T _{MIN} to T _{MAX} 12-Bit Monotonic T _{MIN} to T _{MAX} 12-Bit Monotonic T _{MIN} to T _{MAX} 12-Bit Monotonic T _{MIN} to T _{MAX} DAC Register Loaded with 1111 1111 1111 Gain Error Is Adjustable Using the Circuits of Figures 4, 5, and 6	
	J, A, S	±2	±2	±2	±2	LSB max		
	K, B, T	±1	±1	±1	±1	LSB max		
	L, C, U	±1/2	±1/2	±1/2	±1/2	LSB max		
	GL, GC, GU	±1/2	±1/2	±1/2	±1/2	LSB max		
Differential Nonlinearity	J, A, S	±4	±4	±4	±4	LSB max		
	K, B, T	±1	±1	±1	±1	LSB max		
	L, C, U	±1	±1	±1	±1	LSB max		
	GL, GC, GU	±1	±1	±1	±1	LSB max		
Gain Error (Using Internal RFB) ²	J, A, S	±20	±20	±25	±25	LSB max		
	K, B, T	±10	±10	±15	±15	LSB max		
	L, C, U	±5	±6	±10	±10	LSB max		
	GL, GC, GU	±1	±2	±6	±7	LSB max		
Gain Temperature Coefficient ³ ΔGain/ΔTemperature	All	±5	±5	±10	±10	ppm/°C max		Typical Value is 2 ppm/°C for V _{DD} = +5 V
DC Supply Rejection ³ ΔGain/ΔV _{DD}	All	0.015	0.03	0.01	0.02	% per % max		ΔV _{DD} = ±5%
Output Leakage Current at OUT1	J, K, L, GL	10	50	10	50	nA max		DB0–DB11 = 0 V; \overline{WR} , \overline{CS} = 0 V
	A, B, C, GC	10	50	10	50	nA max		
	S, T, U, GU	10	200	10	200	nA max		
DYNAMIC PERFORMANCE								
Current Settling Time ³	All	2	2	2	2	μs max	To 1/2 LSB. OUT1 Load = 100 Ω. DAC Output Measured from Falling Edge of \overline{WR} , \overline{CS} = 0.	
Propagation Delay ³ (from Digital Input Change to 90% of Final Analog Output)	All	300	–	250	–	ns max	OUT1 Load = 100 Ω, C _{EXT} = 13 pF ⁴	
Digital-to-Analog Glitch Impulse AC Feedthrough ⁵	All	400	–	250	–	nV sec typ	V _{REF} = AGND	
At OUT1	All	5	5	5	5	mV p-p typ	V _{REF} = ±10 V, 10 kHz Sinewave	
REFERENCE INPUT								
Input Resistance (Pin 19 to GND)	All	7	7	7	7	kΩ min	Input Resistance TC = –300 ppm/°C typ Typical Input Resistance = 11 kΩ	
		25	25	25	25	kΩ max		
ANALOG OUTPUT								
Output Capacitance ³								
C _{OUT1}	All	70	70	70	70	pF max	DB0–DB11 = 0 V, \overline{WR} , \overline{CS} = 0 V	
C _{OUT1}		200	200	200	200	pF max	DB0–DB11 = V _{DD} , \overline{WR} , \overline{CS} = 0 V	
DIGITAL INPUTS								
Input High Voltage								
V _{IH}	All	2.4	2.4	13.5	13.5	V min	V _{IN} = 0 or V _{DD} V _{IN} = 0 V _{IN} = 0	
Input Low Voltage								
V _{IL}	All	0.8	0.8	1.5	1.5	V max		
Input Current ⁶								
I _{IN}	All	±1	±10	±1	±10	μA max		
Input Capacitance ³								
DB0–DB11	All	5	5	5	5	pF max	V _{IN} = 0	
\overline{WR} , \overline{CS}	All	20	20	20	20	pF max	V _{IN} = 0	
SWITCHING CHARACTERISTICS ⁷								
Chip Select to Write Setup Time	All	280	380	180	200	ns min	See Timing Diagram	
t _{CS}		200	270	120	150	ns typ		
Chip Select to Write Hold Time							t _{CS} ≥ t _{WR} , t _{CH} ≥ 0	
t _{CH}	All	0	0	0	0	ns min		
Write Pulse Width								
t _{WR}	All	250	400	160	240	ns min		
		175	280	100	170	ns typ		
Data Setup Time	All	140	210	90	120	ns min		
t _{DS}		100	150	60	80	ns typ		
Data Hold Time								
t _{DH}	All	10	10	10	10	ns min		
POWER SUPPLY								
I _{DD}	All	2	2	2	2	mA max	All Digital Inputs V _{IL} or V _{IH} All Digital Inputs 0 V to V _{DD} All Digital Inputs 0 V to V _{DD}	
		100	500	100	500	μA max		
		10	10	10	10	μA typ		

NOTES

¹Temperature range as follows: J, K, L, GL versions, 0°C to +70°C; A, B, C, GC versions, –25°C to +85°C; S, T, U GU versions, –55°C to +125°C.

²This includes the effect of 5 ppm max gain TC.

³Guaranteed but not tested.

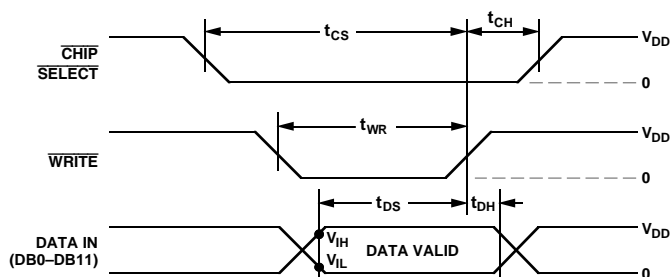
⁴DB0–DB11 = 0 V to V_{DD} or V_{DD} to 0 V.

⁵Feedthrough can be further reduced by connecting the metal lid on the ceramic package (Suffix D) to DGND.

⁶Logic inputs are MOS gates. Typical input current (+25°C) is less than 1 nA.

⁷Sample tested at +25°C to ensure compliance.

Specifications subject to change without notice.



Write Cycle Timing Diagram

ABSOLUTE MAXIMUM RATINGS*(T_A = +25°C unless otherwise noted)

V _{DD} to DGND	−0.3, +17 V
Digital Input Voltage to DGND	−0.3 V, V _{DD} + 0.3 V
V _{RFB} , V _{REF} to DGND	±25 V
V _{PIN1} to DGND	−0.3 V, V _{DD} + 0.3 V
AGND to DGND	−0.3 V, V _{DD} + 0.3 V
Power Dissipation (Any Package) to +75°C	450 mW
Derates above +75°C	6 mW/°C
Operating Temperature	

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD7545 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

TERMINOLOGY**RELATIVE ACCURACY**

The amount by which the D/A converter transfer function differs from the ideal transfer function after the zero and full-scale points have been adjusted. This is an endpoint linearity measurement.

DIFFERENTIAL NONLINEARITY

The difference between the measured change and the ideal change between any two adjacent codes. If a device has a differential nonlinearity of less than 1 LSB it will be monotonic, i.e., the output will always increase for an increase in digital code applied to the D/A converter.

PROPAGATION DELAY

This is a measure of the internal delay of the circuit and is measured from the time a digital input changes to the point at which the analog output at OUT1 reaches 90% of its final value.

DIGITAL-TO-ANALOG GLITCH IMPULSE

This is a measure of the amount of charge injected from the digital inputs to the analog outputs when the inputs change state. It is usually specified as the area of the glitch in nV secs and is measured with V_{REF} = AGND and an ADLH0032CG as the output op amp, C1 (phase compensation) = 33 pF.

MODE SELECTION

WRITE MODE:	HOLD MODE:
\overline{CS} and \overline{WR} LOW, DAC RESPONDS TO DATA BUS (DB0-DB11) INPUTS.	EITHER \overline{CS} OR \overline{WR} HIGH, DATA BUS (DB0-DB11) IS LOCKED OUT; DAC HOLDS LAST DATA PRESENT WHEN \overline{WR} OR \overline{CS} ASSUMED HIGH STATE.

NOTES:V_{DD} = +5V; t_r = t_f = 20nsV_{DD} = +15V; t_r = t_f = 40nsALL INPUT SIGNAL RISE AND FALL TIMES MEASURED FROM 10% TO 90% OF V_{DD}.TIMING MEASUREMENT REFERENCE LEVEL IS V_{IH} + V_{IL}/2.

Commercial (J, K, L, GL) Grades	0°C to +70°C
Industrial (A, B, C, GC) Grades	−25°C to +85°C
Extended (S, T, U, GU) Grades	−55°C to +125°C
Storage Temperature	−65°C to +150°C
Lead Temperature (Soldering, 10 secs)	+300°C

*Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**ORDERING GUIDE¹**

Model ²	Temperature Range	Relative Accuracy	Maximum Gain Error T _A = +25°C V _{DD} = +5 V	Package Options ³
AD7545JN	0°C to +70°C	±2 LSB	±20 LSB	N-20
AD7545AQ	−25°C to +85°C	±2 LSB	±20 LSB	Q-20
AD7545SQ	−55°C to +125°C	±2 LSB	±20 LSB	Q-20
AD7545KN	0°C to +70°C	±1 LSB	±10 LSB	N-20
AD7545BQ	−25°C to +85°C	±1 LSB	±10 LSB	Q-20
AD7545TQ	−55°C to +125°C	±1 LSB	±10 LSB	Q-20
AD7545LN	0°C to +70°C	±1/2 LSB	±5 LSB	N-20
AD7545CQ	−25°C to +85°C	±1/2 LSB	±5 LSB	Q-20
AD7545UQ	−55°C to +125°C	±1/2 LSB	±5 LSB	Q-20
AD7545GLN	0°C to +70°C	±1/2 LSB	±1 LSB	N-20
AD7545GCQ	−25°C to +85°C	±1/2 LSB	±1 LSB	Q-20
AD7545GUQ	−55°C to +125°C	±1/2 LSB	±1 LSB	Q-20
AD7545JP	0°C to +70°C	±2 LSB	±20 LSB	P-20A
AD7545SE	−55°C to +125°C	±2 LSB	±20 LSB	E-20A
AD7545KP	0°C to +70°C	±1 LSB	±10 LSB	P-20A
AD7545TE	−55°C to +125°C	±1 LSB	±10 LSB	E-20A
AD7545LP	0°C to +70°C	±1/2 LSB	±5 LSB	P-20A
AD7545UE	−55°C to +125°C	±1/2 LSB	±5 LSB	E-20A
AD7545GLP	0°C to +70°C	±1/2 LSB	±1 LSB	P-20A
AD7545GUE	−55°C to +125°C	±1/2 LSB	±1 LSB	E-20A

NOTES

¹Analog Devices reserves the right to ship either ceramic (D-20) in lieu of cerdip packages (Q-20).

²To order MIL-STD-883, Class B process parts, add /883B to part number. Contact local sales office for military data sheet. For U.S. Standard Military DRAWING (SMD) see DESC drawing 5962-87702.

³E = Leadless Ceramic Chip Carrier; N = Plastic DIP; P = Plastic Leaded Chip Carrier; Q = Cerdip.